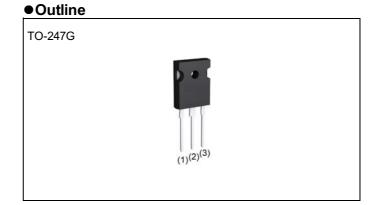
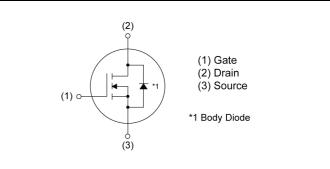
V _{DSS}	600V
R _{DS(on)} (Max.)	0.234Ω
Ι _D	±20A
P _D	252W



Inner circuit



Application

Features

2) Low on-resistance3) Fast switching speed

1) Fast reverse recovery time (trr)

4) Drive circuits can be simple

5) Pb-free plating ; RoHS compliant

Switching applications

Packaging specifications

Packing	Tube
Packing code	C13
Marking	R6020JNZ4
Basic ordering unit (pcs)	600

• Absolute maximum ratings (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V _{DSS}	600	V
Continuous drain current $(T_c = 25^{\circ}C)$	I _D *1	±20	А
Pulsed drain current	I _{DP} ^{*2}	±60	А
Gate - Source voltage	V _{GSS}	±30	V
Avalanche current, single pulse	I _{AS} *3	4.8	А
Avalanche energy, single pulse	E _{AS} *3	618	mJ
Power dissipation $(T_c = 25^{\circ}C)$	P _D	252	W
Junction temperature	Tj	150	°C
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C

•Thermal resistance

Deremeter	Cumph of	Values			Lincit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{thJC}	-	-	0.49	°C/W
Thermal resistance, junction - ambient	R _{thJA}	-	-	30	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C

•Electrical characteristics (T_a = 25°C)

Deremeter	Sumpleal	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage		V _{GS} = 0V, I _D = 1mA	600	-	-	V
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 600V, V_{GS} = 0V$ $T_j = 25^{\circ}C$	-	-	100	μA
Gate - Source leakage current	I _{GSS}	V _{GS} = ±30V, V _{DS} = 600V	-	-	±100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 3.5 \text{mA}$	5.0	6.0	7.0	V
Static drain - source on - state resistance R _{DS(on)} *5		V_{GS} = 15V, I _D = 10A T _j = 25°C	-	0.180	0.234	Ω
Gate resistance	R _G	f = 1MHz, open drain	-	2.0	-	Ω



• Electrical characteristics (T_a = 25°C)

Deremeter	Cump of	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Input capacitance	C _{iss}	V _{GS} = 0V	-	1500	-		
Output capacitance	C _{oss}	V _{DS} = 100V	-	90	-		
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	1.9	-	_	
Effective output capacitance energy related	C _{o(er)} *6	V _{GS} = 0V	-	68	-	pF	
Effective output capacitance time related	C _{o(tr)} *7	$V_{DS} = 0V$ to 480V	-	270	-		
Turn - on delay time	t _{d(on)} *5	$V_{DD} \simeq 300$ V, V_{GS} = 15V	-	29	-		
Rise time	t _r *5	I _D = 10A	-	22	-	20	
Turn - off delay time	t _{d(off)} *5	$R_L \simeq 30.1\Omega$	-	56	-	ns	
Fall time	t _f *5	R _G = 10Ω	-	13	-		

• Gate charge characteristics ($T_a = 25^{\circ}C$)

Deremeter	Cumph of	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	Q _g *5	$V_{DD} \simeq 300 V$	-	45	-	
Gate - Source charge	Q _{gs} *5	I _D = 20A	-	15	-	nC
Gate - Drain charge	Q_{gd}^{*5}	V _{GS} = 15V	-	17	-	
Gate plateau voltage	V _(plateau)	$V_{DD} \simeq 300$ V, I _D = 20A	-	9.5	-	V

*1 Limited only by maximum temperature allowed.

*2 Pw \leq 10µs, Duty cycle \leq 1%

*3 L \simeq 50mH, V_{DD} = 50V, R_G = 25 Ω , starting T_i = 25°C

- *4 Tc=25°C
- *5 Pulsed
- *6 Co(er) is a fixed capacitance that gives the same stored energy as Coss while V_{DS} is rising from 0 to 80% V_{DSS} .
- *7 Co(tr) is a fixed capacitance that gives the same charging time as Coss while V_{DS} is rising from 0 to 80% V_{DSS} .



•Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Source current I _S *1		T - 25°0	-	-	20	А
Pulsed source current	I_{SP}^{*2}	T _C = 25°C	-	-	60	А
Source-Drain voltage	V_{SD}^{*5}	V _{GS} = 0V, I _S = 20A	-	-	1.7	V
Reverse recovery time	t _{rr} *5		-	85	-	ns
Reverse recovery charge	Q _{rr} *5	Q_{rr}^{*5} $I_S = 20A$ di/dt = 100A/µs	-	280	-	nC
Peak reverse recovery current	۲ <mark>, *</mark> 5		-	7.5	-	А



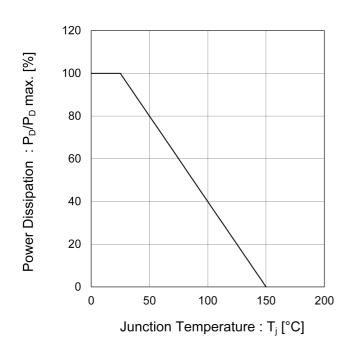
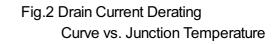


Fig.1 Power Dissipation Derating Curve



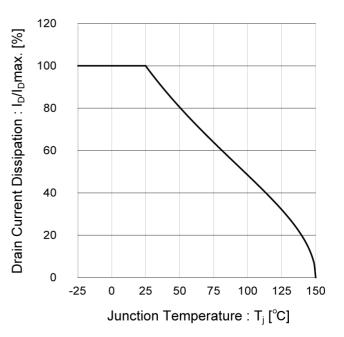


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

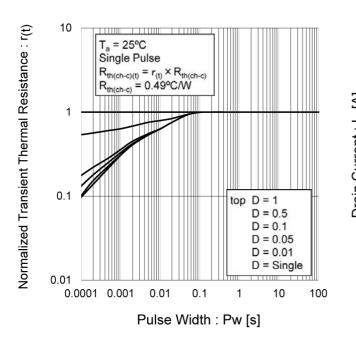
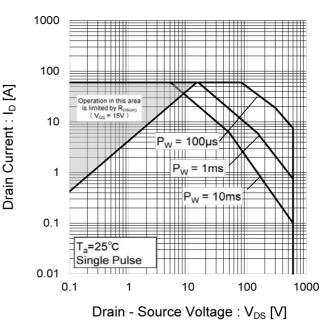


Fig.4 Maximum Safe Operating Area





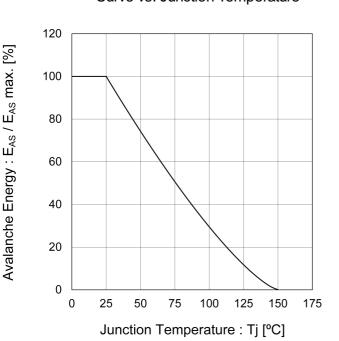




Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

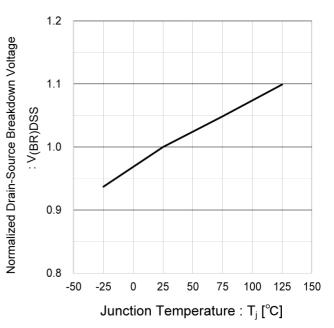


Fig.7 Typical Output Characteristics(I)

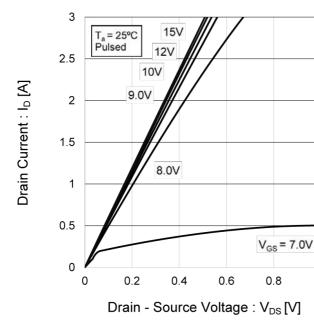
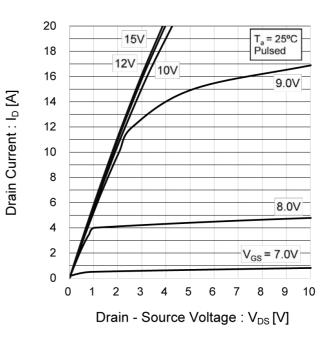


Fig.8 Typical Output Characteristics(II)



ROHM

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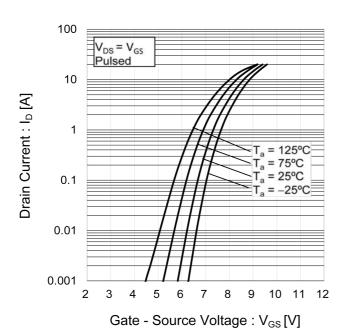


Fig.9 Typical Transfer Characteristics

Fig.10 Normalized Gate Threshold . Voltage vs Junction Temperature

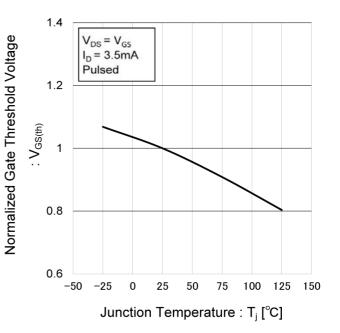
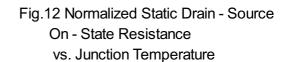
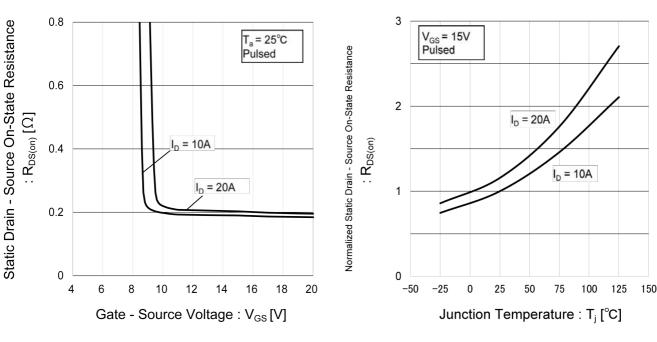


Fig.11 Static Drain - Source On - State Resistance vs. Gate Source Voltage







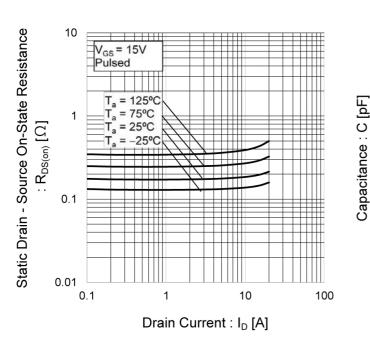


Fig.13 Static Drain - Source On - State

Resistance vs. Drain Current(I)



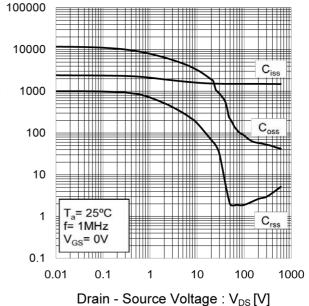
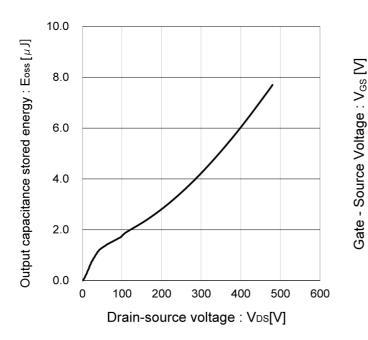
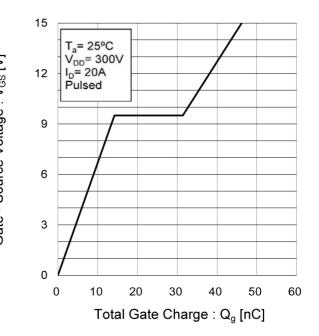


Fig.15 Typical Coss Stored Energy

Fig.16 Dynamic Input Characteristics







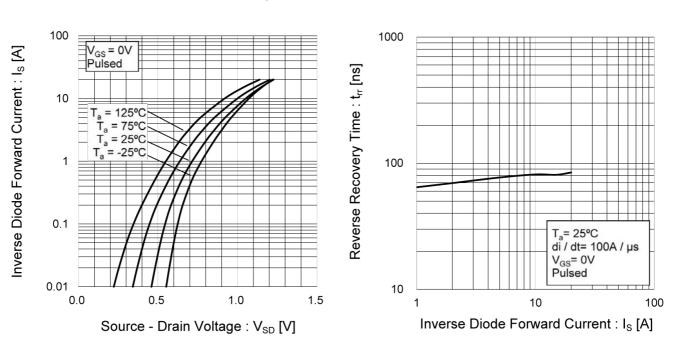
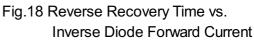


Fig.17 Inverse Diode Forward Current vs. Source - Drain Voltage





Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

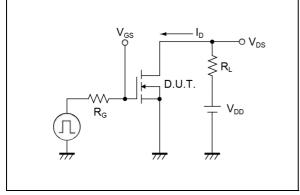


Fig.2-1 Gate Charge Measurement Circuit

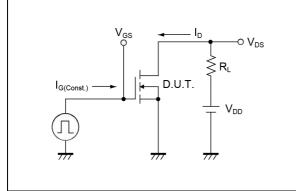


Fig.3-1 Avalanche Measurement Circuit

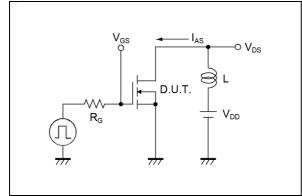


Fig.4-1 Diode Recovery Measurement Circuit

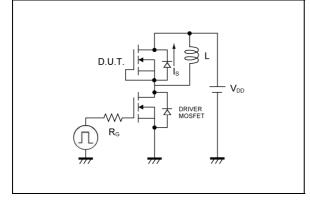


Fig.1-2 Switching Waveforms

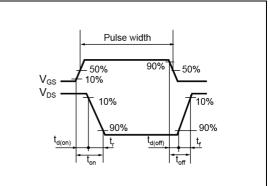


Fig.2-2 Gate Charge Waveform

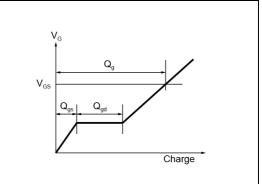


Fig.3-2 Avalanche Waveform

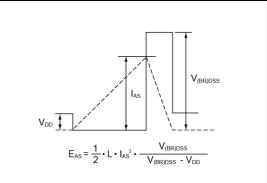
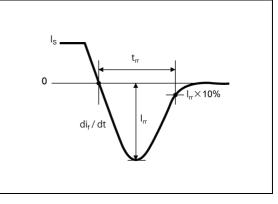
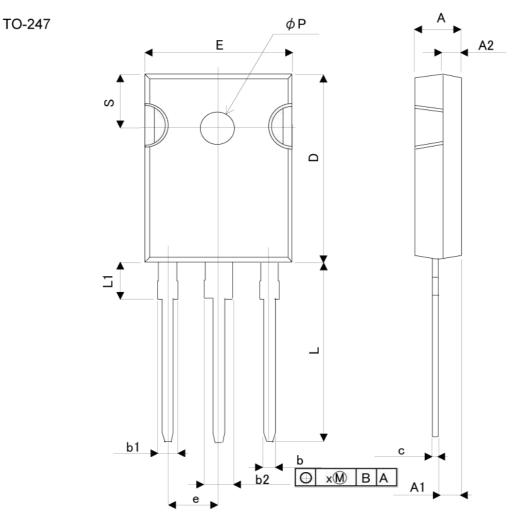


Fig.4-2 Diode Recovery Waveform





Dimensions



DIM	MILIM	ETERS	INC	HES
	MIN	MAX	MIN	MAX
A	4.82	5.22	0.190	0.206
A1	2.11	2.71	0.083	0.107
A2	1.80	2.20	0.071	0.087
b	1.00	1.40	0.039	0.055
b1	1.80	2.20	0.071	0.087
b2	2.80	3.20	0.110	0.126
с	0.45	0.75	0.018	0.030
D	20.65	21.25	0.813	0.837
E	15.64	16.24	0.616	0.639
е	5.4	44	0.2	14
L	19.77	20.37	0.778	0.802
L1	4.09	4.29	0.161	0.169
Р	3.51	3.71	0.138	0.146
S	5.97	6.37	0.235	0.251

Dimension in mm/inches



Notice

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1. Our Products are designed and manufactured for application in ordinary electronic equipment (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (^{Note 1}), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

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CLASSⅢ	CLASSⅢ	CLASS II b	CLASSII
CLASSⅣ	CLASSIII	CLASSII	CLASSI

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 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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 - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

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Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

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